

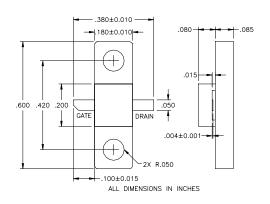
EFC240B-180F

Low Distortion GaAs Power FET

ISSUED 10/04/2006

FEATURES

- NON-HERMETIC 180MIL METAL FLANGE PACKAGE
- +31.0 dBm TYPICAL OUTPUT POWER
- 16.5 dB TYPICAL POWER GAIN AT 2GHz
- 0.3 x 2400 MICRON RECESSED "MUSHROOM" GATE
- Si₃N₄ PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY



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Caution! ESD sensitive device.

ELECTRICAL CHARACTERISTICS (T_a = 25°C)

SYMBOL	PARAMETERS/TEST CONDITIONS ¹		MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression V_{DS} = 10 V, I_{DS} ≈ 50% I_{DSS}	f = 2GHz f = 4GHz	29.0	31.0 31.0		dBm
G _{1dB}	Gain at 1dB Compression V_{DS} = 10 V, $I_{DS} \approx 50\% I_{DSS}$	f = 2GHz f = 4GHz	15.0	16.5 11.5		dB
PAE	Power Added Efficiency at 1dB Compression V_{DS} = 10 V, I_{DS} ≈ 50% I_{DSS} f = 2GHz			40		%
I _{DSS}	Saturated Drain Current V _c	$_{OS}$ = 3 V, V_{GS} = 0 V	320	520	720	mA
G _M	Transconductance V	$_{DS} = 3 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	200	280		mS
V_P	Pinch-off Voltage V _{DS}	= 3 V, I _{DS} = 6 mA		-2.5	-4.0	V
BV _{GD}	Drain Breakdown Voltage I _{GD} =	= 2.4 mA	-18	-20		V
BV _{GS}	Source Breakdown Voltage I _{GS} =	= 2.4 mA	-10	-17		V
R _{th}	Thermal Resistance			22*		°C/W

^{*} Overall Rth depends on case mounting.

MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²
V_{DS}	Drain-Source Voltage	15V	10V
V_{GS}	Gate-Source Voltage	5V	-4.5V
lgf	Forward Gate Current	10.8mA	3.6mA
lgr	Reverse Gate Current	-1.8mA	-0.6mA
Pin	Input Power	29dBm	@ 3dB Compression
Tch	Channel Temperature	175°C	175°C
Tstg	Storage Temperature	-65/175°C	-65/175°C
Pt	Total Power Dissipation	6W	6W

Note: 1. Exceeding any of the above ratings may result in permanent damage.

^{2.} Exceeding any of the above ratings may reduce MTTF below design goals.